Preface of the 2012 IAENG International Conference on Electrical Engineering Special Session: Design, Analysis and Tools for Integrated Circuits and Systems

The International Workshop DATICS-IMECS'12: Design, Analysis and Tools for Integrated Circuits and Systems in the International MultiConference of Engineers and Computer Scientists 2012 will take place in Hong Kong, 14-16 March, 2012.

DATICS Workshops were initially created by a network of researchers and engineers both from academia and industry in the areas of Design, Analysis and Tools for Integrated Circuits and Systems. Recently, DATICS has been extended to the fields of Communication, Computer Science, Software Engineering and Information Technology.

The main target of DATICS-IMECS'12 is to bring together software/hardware engineering researchers, computer scientists, practitioners and people from industry to exchange theories, ideas, techniques and experiences related to all aspects of DATICS.

The International Program Committee (IPC) of DATICS-IMECS'12 consists of about 150 experts in the related fields of DATICS-IMECS'12 both from academia and industry. DATICS-IMECS'12' is partnered with CEOL: Centre for Efficiency-Oriented Languages (Ireland), International Software and Productivity Engineering Institute (USA), Intelligent Support Ltd., (United Kingdom), Minteos (Italy), Electronic Center (Italy), Legale Fiscale (Italy), LS Industrial Systems (South Korea), Solari (Hong Kong), Ejitec (China) and Xi'an Jiaotong-Liverpool University - XJTLU (China - UK), Distributed Thought (UK), ASIC Design Lab - Myongji University (South Korea) and Katri (Hong Kong and Japan).

DATICS-IMECS'12 received 19 full-paper submissions from 10 different countries around the world. These submissions were sent to the members of the IPC and additional reviewers for review. Every submission received at least two independent reviews. We would like to thank the IPC members and the reviewers for their hard work and dedication. The DATICS-IMECS'12 Technical Program includes 9 papers (acceptance rate of 47 %) which are organized into lecture sessions.

On behalf of the IPC, we would like to welcome the delegates and their guests to the DATICS-IMECS'12. We hope that you will enjoy the workshop and find the DATICS-IMECS'12 Technical Program exciting.

Ka Lok Man, Chi-Un Lei, Tomas Krilavičius and Michele Mercaldi (DATICS-IMECS'12 Chairs).

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- Gregory Provan, University College Cork, Ireland
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- Ngo Quoc Tao, Vietnamese Academy of Science and Technology, Vietnam
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- Matthieu Moy, Verimag Laboratory, France
- Ramy Iskander, LIP6 Laboratory, France
- Suryaprasad Jayadevappa, PES School of Engineering, India
- Shanmugasundaram Hariharan, Pavendar Bharathidasan College of Engineering and Technology, India

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- Chelho Chung, System Semiconductor/Central R&D Center, LS Industrial Systems, South Korea
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- Nicolas Vallee, ENSTA, France
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